

## **Description**

The SI2333CDS-T1-GE3 uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 2.5V.This device is suitable for use as a Battery protection or in other Switching application.

# D S S G SOT-23-3L

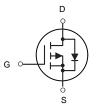
#### **General Features**

 $V_{DS} = -20V, I_{D} = -7A$ 

 $R_{DS(ON)}$  < 22m $\Omega$  @  $V_{GS}$ =4.5V

### **Application**

High power and current handing capability
Lead free product is acquired
Surface mount package
PWM applications
Load switch
Power management



P-Channel MOSFET

## **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
SI2333CDS-T1-GE3	SOT-23-3L	20P07	3000PCS

## Absolute Maximum Ratings (T<sub>A</sub>=25 ℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>DS</sub>	Drain-Source Voltage	-20	V
V <sub>G</sub> s	Gate-Source Voltage	±12	V
ID	Drain Current-Continuous	-7	А
Ірм	Drain Current-Pulsed (Note 1)	-18.8	А
Po	Maximum Power Dissipation	1	W
T <sub>J</sub> ,T <sub>STG</sub>	Operating Junction and Storage Temperature Range		°C
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	125	°C/W

#### P-Channel Enhancement Mode MOSFET

### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0 $V$ , $I_D$ =-250 $u$ A	-20			<b>V</b>
$\triangle BV_{DSS} /\!\!\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA		-0.01		V/°C
	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-6.5A		18	22	mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =-2.5V , I <sub>D</sub> =-5A		25	39	
		V <sub>GS</sub> =-1.8V , I <sub>D</sub> =-1.5A				
V <sub>GS(th)</sub>	Gate Threshold Voltage	V -V I - 250	-0.6	-0.8	-1.4	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=-250uA$				mV/°C
	Drain-Source Leakage Current	V <sub>DS</sub> =-20V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			-1	
I <sub>DSS</sub>		V <sub>DS</sub> =-16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C				uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =± 12V , V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-3A		10		S
Qg	Total Gate Charge (-4.5V)			10		
Q <sub>gs</sub>	Gate-Source Charge $V_{DS}$ =-10V , $V_{GS}$ =	V <sub>DS</sub> =-10V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-6 <b>A</b> 5		1.5		nC
Q <sub>gd</sub>	Gate-Drain Charge			3		
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ =-10V , $V_{GS}$ =-4.5V , $R_{G}$ =6.0 $\Omega$		30		
Tr	Rise Time			25		
T <sub>d(off)</sub>	Turn-Off Delay Time			70		ns
T <sub>f</sub>	Fall Time			50		
Ciss	Input Capacitance			1210		
Coss	Output Capacitance	V <sub>DS</sub> =-10V , V <sub>GS</sub> =0V , f=1MHz		310		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			290		

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,4</sup>				-7.0	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-18.8	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C			-1	V
t <sub>rr</sub>	Reverse Recovery Time			52		nS
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =-4A , dI/dt=100A/μs , T <sub>J</sub> =25°C		28		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300 \text{us}$  , duty cycle  $\leq 2\%$
- 3. The power dissipation is limited by 150°C junction temperature
- ${}_{4.}\text{The data is theoretically the same as } I_{\text{D}} \text{ and } I_{\text{DM}}, \text{ in real applications }, \text{ should be limited by total power dissipation.}$



#### **Typical Characteristics**

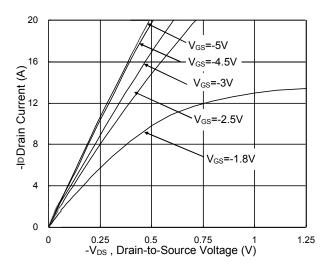


Fig.1 Typical Output Characteristics

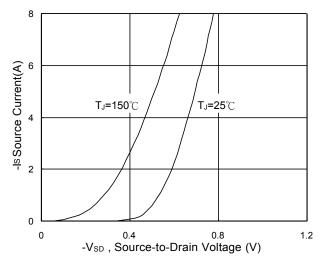


Fig.3 Forward Characteristics Of Reverse

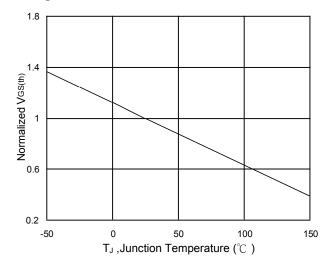


Fig.5 Normalized  $V_{\text{GS(th)}}$  vs.  $T_{\text{J}}$ 

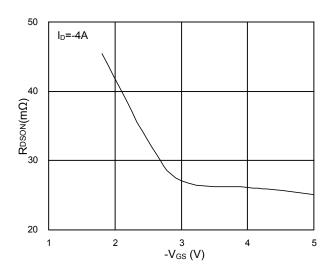


Fig.2 On-Resistance vs. Gate-Source

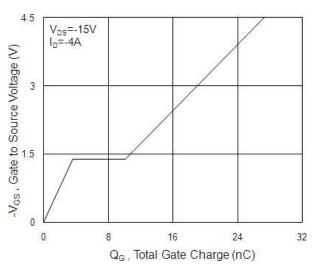


Fig.4 Gate-Charge Characteristics

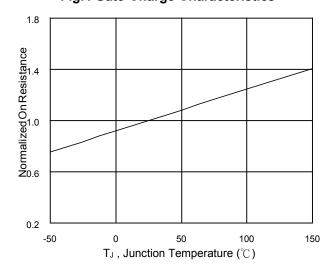
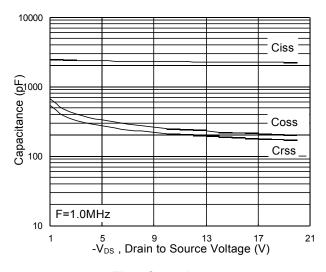


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





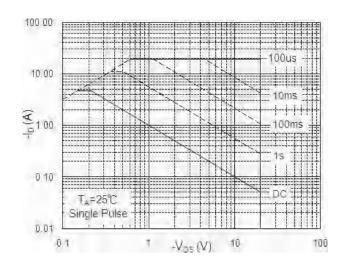


Fig.7 Capacitance

Fig.8 Safe Operating Area

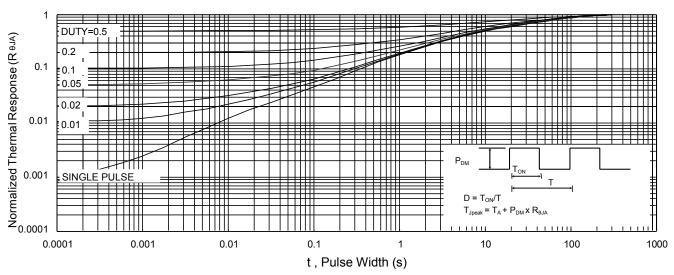


Fig.9 Normalized Maximum Transient Thermal Impedance

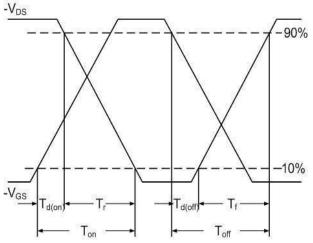


Fig.10 Switching Time Waveform

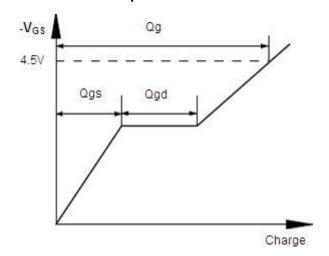
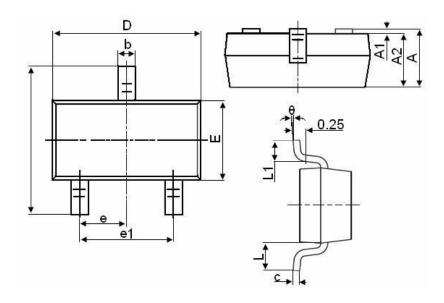


Fig.11 Gate Charge Waveform

# **SOT-23-3L Package Information**



Symbol	Dimensions in Millimeters		
	MIN.	MAX.	
А	1.050	1.250	
A1	0.000	0.100	
A2	1.050	1.150	
b	0.300	0.500	
С	0.100	0.200	
D	2.800	3.000	
E	1.500	1.700	
E1	2.650	2.950	
е		0.950TYP	
e1	1.800	2.000	
L		0.550REF	
L1	0.300	0.600	
θ	0°	8°	

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